

Appl. No. 10/774,551
Amdt. Dated June 27, 2005
Reply to Office Action of March 25, 2005

Attorney Docket No. 81716.0120
Customer No.: 26021

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims 1-8. (Canceled).

Claim 9 (Currently amended): A ceramic circuit board comprising:
a ceramic substrate having a through hole;
a metal column arranged within the through hole; and
metal circuit plates attached to both surfaces of the ceramic substrate
in such a way as to stop up the through hole,
wherein the metal circuit plates attached to both surfaces of the
ceramic substrate are connected to each other by the metal column,
and wherein, between an inner wall surface of the through hole and an
outer wall surface of the metal column is secured a space defining a cavity which is
~~30 to 200 μ m long.~~

Claim 10 (Original): The ceramic circuit board of claim 9,
wherein the metal circuit plate is made of copper or aluminum.

Claim 11 (Original): The ceramic circuit board of claim 9,
wherein the metal column is made of copper or aluminum.

Claims 12-15 (Canceled).

Claim 16 (New): The ceramic circuit board of claim 9,

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wherein the space defining the cavity exists along the entire length of the metal column.

Claim 17 (New): The ceramic circuit board of claim 9,
wherein a distance between the inner wall surface of the through hole and the outer wall surface of the metal column is in a range of 30 to 200 μm .

Claim 18 (New): The ceramic circuit board of claim 9,
wherein the metal circuit plate has its surface plated with a layer made of nickel.

Claim 19 (New): The ceramic circuit board of claim 18,
wherein the plate layer is made of a nickel-phosphorous amorphous alloy containing phosphorous in an amount of 8 to 15 wt%.

Claim 20 (New): The ceramic circuit board of claim 18,
wherein the plate layer is 1.5 to 3 μm thick.

Claim 21 (New): The ceramic circuit board of claim 9,
wherein the metal column has a diameter of 200 μm or above.